

Ultra Large band Silicon Capacitor ULSC722.410

0201M 1nF BV30



Rev. 1.03

General description

Market: ULSC Capacitor targets Optical communication system such as ROSA/TOSA, SONET and all optoelectronics as well as High speed data system or products.

The ULSC is suitable for DC blocking, feedback, coupling and bypassing applications in all broadband optoelectronics and High-speed data system.

The unique technology of integrated passive device in silicon, developed by Murata Integrated Passive Solutions, offers unique performances with low insertion loss, low reflection and phase stability from 1600 KHz to 20 GHz.

These capacitors in ultra-deep trenches in silicon have been developed in a semiconductor process, in order to integrate trench MOS capacitor providing high capacitance value of 1nF (for kHz–MHz range) and MIM capacitors for low capacitance value (for GHz range), both in a SMT 0201M (0.6 x 0.3mm).

The ULSC capacitor provides very high stability of the capacitance over temperature, voltage variation as well as a very high reliability.

ULSC capacitors have an extended operating temperature ranging from -55 to 150°C, with very low capacitance change over temperature (+70ppm/K).

Assembly: flip chip applications through existing laminated packages or rigid PCB, ceramic substrate, FR4 or flex platforms suitable.

Bump finishing: SAC305 type 6.

Key features

- Ultra large band performance to 20 GHz
- Resonance free
- Phase stability
- Insertion low < 0.2dB Typ. up to 20 GHz
- Ultra-high stability of capacitance value:
 - Temperature 70ppm/K (-55 °C to +150 °C)
 - Voltage <0.1%/Volts
 - Negligible capacitance loss through ageing
- Low profile: 140µm including bump height
- Break down voltage : 30V
- Low leakage current < 100pA
- High reliability
- High operating temperature (up to 150 °C)
- Compatible with high temperature cycling during manufacturing operations (exceeding 300 °C)
- Compatible with EIA 0201 footprint
- SAC305 40µm bumps after reflow

Key applications

- ROSA/TOSA
- SONET
- High speed digital logic
- Microwave/millimetre system
- High volumetric efficiency (i.e. *capacitance* per unit *volume*)
- Broadband test equipment



Functional diagram

The next figure provides implementation set-up diagram.



Figure 1 Block Diagram

Electrical performances

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
C	Capacitance value	@+25°C	-	1	-	nF
ΔC_P	Capacitance tolerance ⁽¹⁾	@+25°C	-15	-	+15	%
T _{OP}	Operating temperature		-55	20	150	°C
T _{STG}	Storage temperature ⁽²⁾		-70	-	165	°C
ΔC_T	Capacitance temperature variation	-55 °C to 150 °C	-	70	-	ppm/K
RV _{DC}	Rated voltage ⁽³⁾		-	-	16 ⁽⁴⁾ 14.7 ⁽⁵⁾	V _{DC}
BV	Break down voltage	@+25°C	30	-	-	V
ΔC_{RVDC}	Capacitance voltage variation	From 0 V to RV _{DC} , @+25°C	-	-	0.1	%/V _{DC}
IR	Insulation resistor	@RV _{DC} , +25°C, 120s	-	10	-	GΩ
ESR	Equivalent Serial Resistance ⁽⁶⁾	@+25°C, shunt mode	-	250	400	mΩ
ESL	Equivalent Serial Inductance ⁽⁶⁾	@+25°C, SRF shunt mode	-	180	-	pH
Fc-3dB	Cut-off frequency at 3dB ⁽⁶⁾	@+25°C	-	1600	1872	kHz
IL	Insertion loss ⁽⁶⁾	@ 20 GHz, +25°C	-	0.2	-	dB
RL	Return loss ⁽⁶⁾	Up to 20 GHz, +25°C	30	-	-	dB
ESD	HBM stress ⁽⁷⁾	JS-001-2017	8	-	-	kV

Table 1 - Electrical performances

(1): other tolerance available upon request

(2): without packaging

(3): Lifetime is voltage and temperature dependent, please refer to application note 'Lifetime of 3D capacitors'

(4): 10 years of intrinsic life time prediction at 100°C continuous operation

(5): 10 years of intrinsic life time prediction at 150°C continuous operation

(6): measured

(7): please refer to application note 'ESD Challenge in 3D Murata Integrated Passive technology'



Module S-parameters of 1nF ULSC in transmission mode

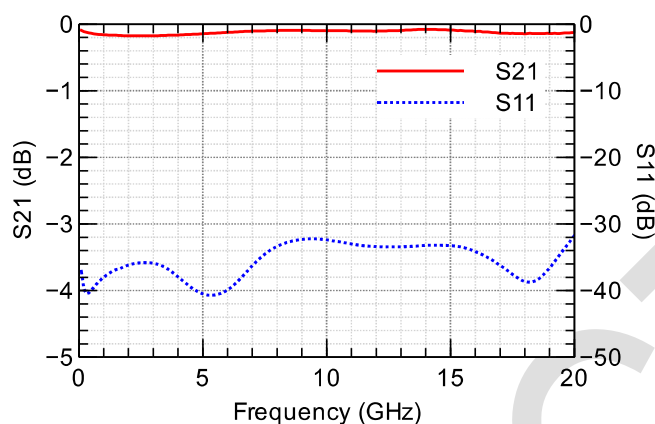
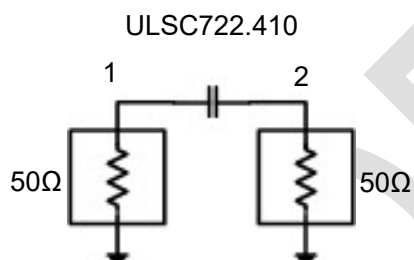


Figure 2 - 1nF ULSC measurement results
(module of S-parameters)

Schematic of 1nF ULSC in transmission mode



4-mil Rogers 4350B.

Microstrip mode – line width = 0.200mm and gap = 0.200 mm.
(nominal 50 ohm characteristic impedance).

Figure 3 – 1nF ULSC measurement schematic

Example of surface mounted 0201M

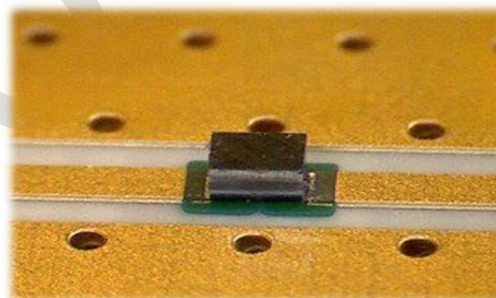


Figure 4 – micro picture of ULSC mounted on board
in coplanar mode



Pinning definition

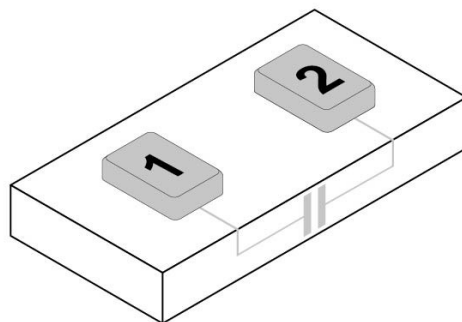


Figure 5 Pin configuration

pin #	Symbol	Coordinates X / Y
1	Signal	-150.0 / 0.0
2	Signal	150.0 / 0.0

Table 2 - Pinning description. Reference (0,0) located at the centre of the die.

Ordering Information

Murata Integrated Passive Devices delivers products with AQL level II (0.65). Tighter quality levels are available upon request.

Part number (16NC)	Package		
	Packaging	Finishing	Description
935156722410-F1S	6" film frame carrier ⁽¹⁾	SAC ⁽²⁾	ULSC 0201M – 1nF – 2 pads – 0.60mm x 0.30mm x 0.14mm
935156722410-T3S	7" T&R (1 000 pieces/reel) ⁽³⁾	SAC ⁽²⁾	ULSC 0201M – 1nF – 2 pads – 0.60mm x 0.30mm x 0.14mm
935156722410-T3N	7" T&R (1 000 pieces/reel) ⁽³⁾	ENIG ⁽²⁾	ULSC 0201M – 1nF – 2 pads – 0.60mm x 0.30mm x 0.14mm

Table 3 - Packaging and ordering information

- (1) Other Film Frame Carrier are possible on request
 (2) ENIG (0.1µm Au / 5µm Ni) + SAC305 type 6
 (3) Missing capacitors can reach 0.5%
 (4) Refer to Figure 7

Product Name (12NC)	Die Name	Description
ULSC722.410	XJM0201410	ULSC 1nF/0201M/BV30 – 2 pads – 0.6 x 0.3 x 0.14 mm ⁽⁴⁾

Table 4 - Die information



Pad Metallization

This surface mounted Silicon Capacitor is delivered as standard with SAC305 bumping.

Other Metallization, such as ENIG, Copper, Thick Gold or Aluminum pads are possible on request.

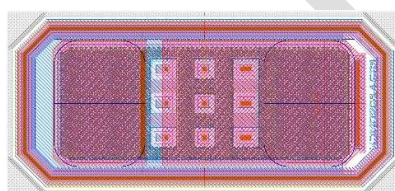
Silicon dies are not sensitive to humidity, please refer to applications notes 'Assembly Notes' section 'Handling precautions and storage'.

Material regulation

This product is RoHS compliant at the time of publication. For further information about regulation compliancy, please ask your sales representative.

Package outline

The product is delivered as a bare silicon die.



Die name

Figure 6 – Layout view

L (mm)	W (mm)	T (mm)	c (mm)	p (mm)	e (mm)	t (mm)
0.60 ± 0.02	0.30 ± 0.02	0.10 ± 0.01	0.10	0.20	0.15	0.04 ⁽¹⁾ 0.05 ⁽²⁾ 0.00 ⁽³⁾

(1) Standard with solder joint height after reflow on board.

(2) Standard with solder bump height before assembly

(3) Only in case of ENIG finishing

Table 5 - Dimensions and tolerances

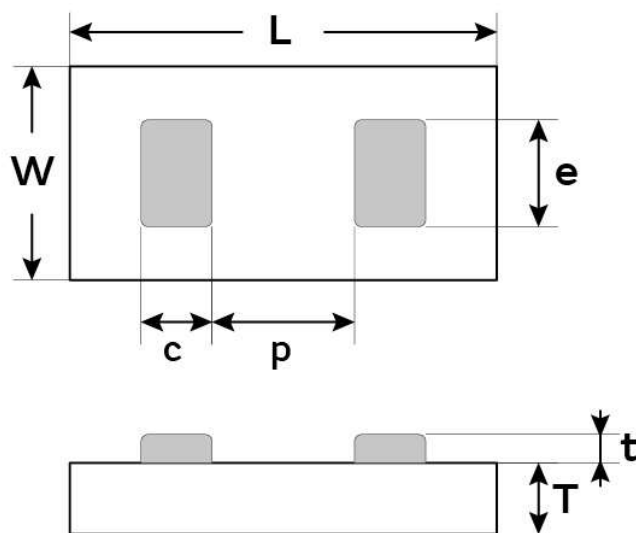


Figure 7 - Package outline drawing

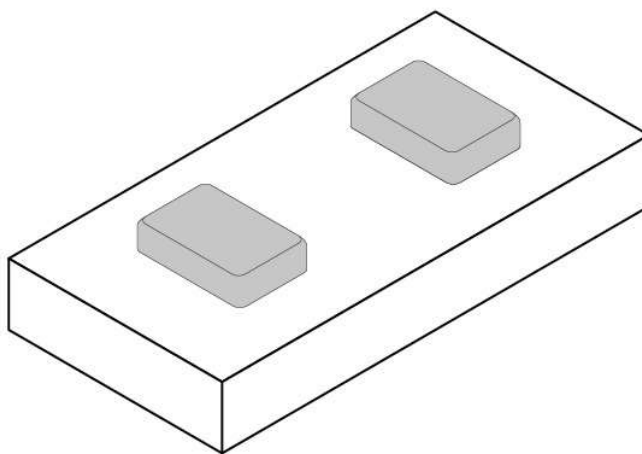


Figure 8 Isometric view



Assembly

ULSC series is compatible with standard reflow technology.

It is recommended to design mirror pads on the PCB.

For further information, please see our mounting application note

The attachment techniques recommended by Murata on the customer's substrates are fully detailed in specific documents available on our website. To assure the correct use and proper functioning of Murata capacitors **please download the assembly instructions on <https://www.murata.com/en-us/products/capacitor/siliconcapacitors> and read them carefully.**



Figure 9 Scan this QR Code to access the Murata Silicon Capacitor web page

Packaging format

Packaging format

Please refer to application note 'Products Storage Conditions and Shelf Life'.

Tape and Reel: Dies are flipped in the tape cavity (bump down) with die ID located near the driving holes of the tape.

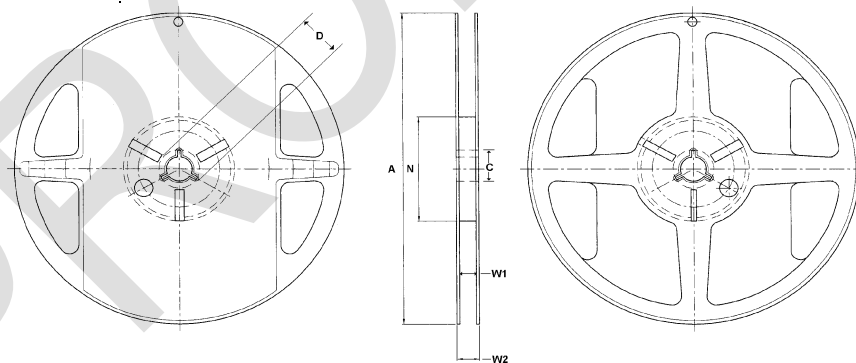


Figure 10 - Reel drawing

Tape Width	Diameter A	C	D	Hub N	W1	W2
8	178 (7 inches)	13.5	21	60	9.5	11.4

Table 6 - Reel dimensions (mm)

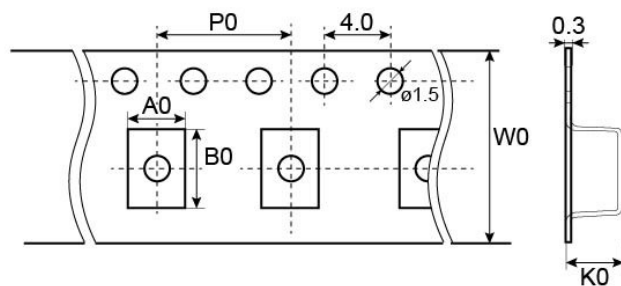


Figure 11 - Tape drawing

Cavity dimensions			Carrier tape width W0	Carrier tape pitch P0	Reel Capacity
A0 (*)	B0 (*)	K0 (*)			
0.36	0.66	0.20	8.00	2.00	1000
0.38	0.68	0.21			

Table 7 - Tape dimensions (mm)

(*) A0, B0 and K0 dimensions depends on the Packaging subcontractor.



Film frame carrier:

With UV curable dicing tape (UV performed)

Good dies are identified using the SINF electronic mapping format. No ink is added on wafer to label other dies.

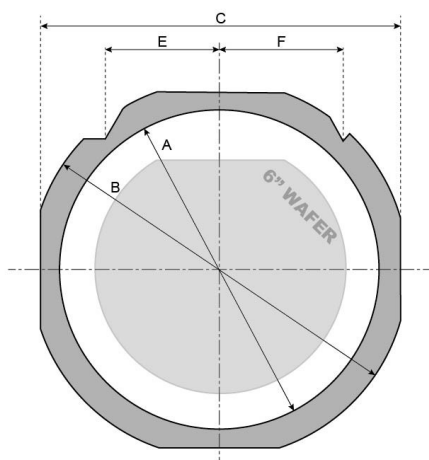


Figure 12 FF070 Frame with a 6" wafer

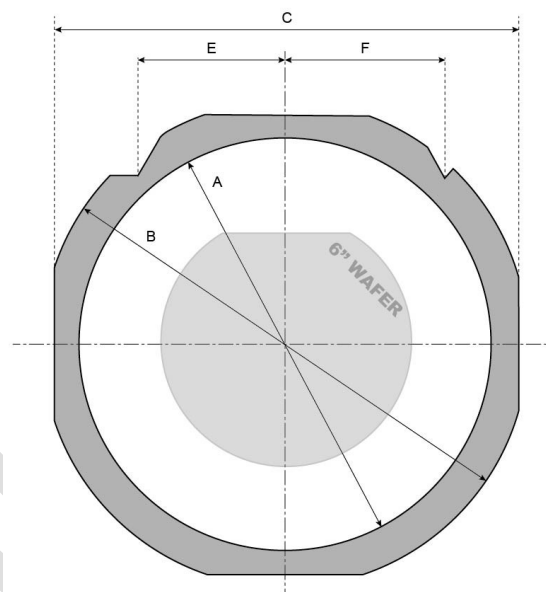


Figure 13 FF108 Frame with a 6" wafer

Frame Reference	Frame Style	Inside diameter A	Outside diameter B	Width C	Thickness	Pin location E	Pin location F
FF070 (1)	DTF-2-6-1	7.638"	8.976"	8.346"	0.048"	2.370"	2.5"
FF108 (1)	DTF-2-8-1	9.842"	11.653"	10.866"	0.048"	2.381"	2.5"

Table 8 - Frame dimensions (inches)

(1) or equivalent



Expander grip ring 6" diameter:

With UV curable dicing tape (UV performed)

Good dies are identified using the SINF electronic mapping format. No ink is added on wafer to label other dies.

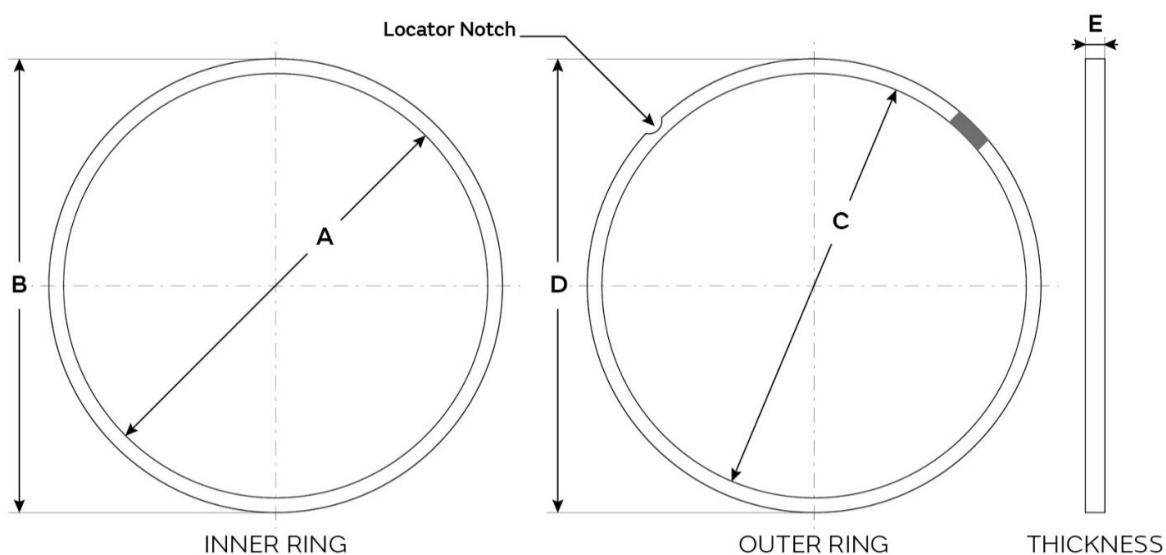


Figure 14 – Grip Ring drawing

Grip Ring Style	A	B	C	D	E	Locator Notch
GRP-2620-6 ⁽¹⁾	7.670"	7.973"	7.975"	8.280"	0.236"	None

Table 9 - Frame dimensions (inches)

(1) or equivalent



Definitions

Data sheet status

Objective specification: This data sheet contains target or goal specifications for product development.

Preliminary specification: This data sheet contains preliminary data; supplementary data may be published later.

Product specification: This data sheet contains final product specifications.

Limiting values

Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those given in the Electrical performances sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

Revision history

Revision	Date	Description	Author
Release 1.00	2017 June 5th	Objective specification	OGA
Release 1.03	2021 Mar. 12th	Minor update	SCA / OGA

Disclaimer / Life support applications

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Murata customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Murata for any damages resulting from such improper use or sale.

Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

Murata Integrated Passive Solutions S.A. makes no representation that the use of its products in the circuits described herein, or the use of other technical information contained herein, will not infringe upon existing or future patent rights. The descriptions contained herein do not imply the granting of licenses to make, use, or sell equipment constructed in accordance therewith. Specifications are subject to change without notice.



www.murata.com

mis@murata.com